**GOVERNMENT - INDUSTRY DATA EXCHANGE PROGRAM**

**PRODUCT CHANGE NOTICE**

1. **TITLE**
   RADHard MOSFET Radiation Test Program Change

2. **DOCUMENT NUMBER**
   FV5-C-17-0021

3. **DATE**
   May 28, 2017

4. **MANUFACTURER AND ADDRESS**
   International Rectifier
   205 Crawford Street
   Leominster, MA 01453

5. **MANUFACTURER PART NUMBER**
   NA

6. **BASE PART**
   NA

7. **NATIONAL STOCK NUMBER (NSN)**
   NA

8. **CAGE**
   69210

9. **EFFECTIVE DATE**
   May 28, 2017

10. **GOVERNMENT NUMBER**
    NA

11. **POINT OF CONTACT**
    Manufacturer’s Representative or
    Customer Service Representative (978) 534-5776

12. **DRAWING NUMBER**
    NA

13. **SPECIFICATION NUMBER**
    MIL-PRF-19500

14. **PRODUCT CHANGE**
    This GIDEP PCN is to announce a change in the Radiation Test Program (TID) at IR HiRel.

    Effective June 1, IR HiRel will no longer offer its RADHard MOSFET parts with 600K Rad(Si) total ionizing dose (TID) test option (identified as IR part number designator “4”). Alternatively we will offer RADHard MOSFET parts tested with 500K Rad(Si) with designator 5. Refer to the “Radiation Level” table below for more designator details and nomenclature in figure 1 herein for reference.

    **RADIATION LEVEL**
    Blank = Non RADHard or 100K Pch (Gen 4 only)
    2 = RADHard 50K Rad(Si)
    3 = RADHard 300K Rad(Si)
    4 = RADHard 600K Rad(Si)
    5 = RADHard 500K Rad(Si)
    7 = RADHard 100K Rad(Si)
    8 = RADHard 1000K Rad(Si)

16. **APPROVING GOVERNMENT ACTIVITY**

17. **GIDEP REPRESENTATIVE**
    Paul Hebert

18. **SIGNATURE**
    [Signature]

19. **DATE**
    May 28, 2017

GIDEP Form 97-5
### Part Number Nomenclature

**RadHard MOSFETs**

**TRANSISTOR TYPE**
- **H** – Radiation Hardened HEXFET
- **HL** – RadHard Logic Level MOSFET
- **HS** – RadHard Synchronous Rectifier
- **HSL** – RadHard Sync. Rectifier (low inductance)

**PACKAGE DESIGNATOR**
All packages have metal lids unless otherwise noted

- **Blank** – Chip / Die (no package)
- **C** – LCC-18
- **EA** – (U6) LCC-28 (single die)
- **F** – TO-205AF (TO-39, low profile)
- **G** – MO-030AB (14 lead ceramic DIP)
- **I** – TO-259AA
- **M** – (T1) TO-254AA
- **MA** – TO-254AA tabless
- **MB** – (D4) TO-254AA tabless, low ohmic
- **MG** – TO-254AA, lead formed
- **MJ** – (D1) TO-254AA tabless, lead formed
- **MK** – TO-254AA tabless, low ohmic, lead formed
- **MS** – TO-254AA low ohmic
- **N** – (U1) SMD-1
- **NA** – (U2) SMD-2
- **NJ** – (U3) SMD-0.5, metal lid
- **NJC** – SMD-0.5, ceramic lid
- **NM** – (U8) SMD-0.2, metal lid
- **NMC** – SMD-0.2, ceramic lid
- **NS** – SupIR-SMD™

- **Q** – LCC-28 (quad die)
- **UB** – LCC-3, metal lid
- **UBC** – LCC-3, ceramic lid, shielded
- **UBCN** – LCC-3, ceramic lid, isolated
- **UBN** – LCC-3, metal lid, isolated
- **UC** – LCC-6
- **V** – (T8) TO-258AA
- **Y** – (T3) TO-257AA
- **YA** – TO-257AA tabless
- **YB** – TO-257AA tabless, low ohmic
- **YG** – TO-257AA, lead formed
- **YJ** – (D3) TO-257AA tabless, lead formed
- **YK** – TO-257AA tabless, low ohmic, lead formed
- **YS** – TO-257AA low ohmic

**TECHNOLOGY**
- **Blank** – Gen 4
- **5** – R5
- **5S** – R5, S-line
- **6** – R6
- **6S** – R6, S-line
- **7** – R7
- **7S** – R7, S-line
- **8** – R8
- **9A** – R9
- **9AS** – R9, S-line

**CHANNEL**
- **Blank** – N-Channel
- **6** – mixed N and P Channel
- **9** – P-Channel

**TOTAL DOSE HARDNESS**
- **Blank** – non-RadHard, or 100 krad(Si) P-Channel (G4 only)
- **2** – 50 krad(Si)
- **3** – 100 krad(Si), N-Channel
- **4** – 600 krad(Si), N-Channel
- **5** – 500 krad(Si), N-channel
- **7** – 100 krad(Si), N-channel
- **8** – 1000 krad(Si), N-Channel

**LEAD OPTION**
- **A** – Lead form down (or if package is SMD, then lead attached)
- **B** – Lead form up (or if package is SMD, then lead attached and formed)
- **C** – Lead trimmed
- **D** – On DBC carrier, applies only to SMD-1 and SMD-2

**SCREENING LEVEL**
- **Blank** – no screening
- **IR HiRel controlled drawing, die level**
- **CDV** – 100% visual screening
- **CDH** – H level
- **CDK** – K level
- **IR HiRel qualified lot, packaged level**
- **SCX** – TX level, equivalent
- **SCV** – TXV level, equivalent
- **SCS** – S level, equivalent

**PROCESS VARIATION**
- **SE** – Single Event Effect tolerant

**VOLTAGE ADDER**
- **Blank** – full spec rating (does not apply to 60V devices)
- **3** – 30 Volts, e.g. 1x3 is 130 Volts
- **4** – 50 Volts, e.g. 2x4 is 250 Volts or, 0x4 is 60 Volts

**DIE SIZE**
- **1** – die size 1
- **2** – die size 1.7 & 2
- **3** – die size 3
- **4** – die size 4
- **5** – die size 5
- **6** – die size 6
- **A** – die size 10
- **Z** – smallest size

**VOLTAGE**
- **0** – 60 Volts
- **1** – 100 Volts (or 130V or 150V with voltage adder)
- **2** – 200 Volts (or 250V with voltage adder)
- **3** – 400 Volts
- **4** – 500 Volts (or 550V with voltage adder)
- **C** – 600 Volts
- **Y** – 20 Volts
- **Z** – 30 Volts